

P-Channel 60 V (D-S) 175 °C MOSFET

PRODUCT SUMMARY			
V _{DS} (V)	$R_{DS(on)}\left(\Omega\right)$	I _D (A) ^c	
- 60	0.0093 at V _{GS} = - 10 V	- 90	
	0.0118 at V _{GS} = - 4.5 V	- 90	

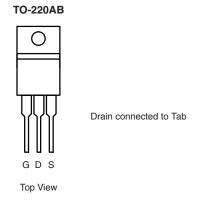
FEATURES

- TrenchFET® Power MOSFET
- Compliant to RoHS Directive 2002/95/EC

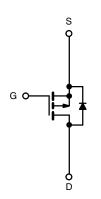


APPLICATIONS

• DC/DC Primary Switch



Ordering Information: SUP90P06-09L-E3 (Lead (Pb)-free)



P-Channel MOSFET

ABSOLUTE MAXIMUM RATINGS (T _C = 25 °C, unless otherwise noted)					
Parameter		Symbol	Limit	Unit	
Drain-Source Voltage		V _{DS}	- 60	V	
Gate-Source Voltage		V _{GS}	± 20		
Continuous Dusin Comment /T 175 9000	T _C = 25 °C	l _D	- 90		
Continuous Drain Current (T _J = 175 °C) ^C	T _C = 125 °C		- 67		
Pulsed Drain Current		I _{DM}	- 200	A	
Avalanche Current	L = 0.1 mH	I _{AS}	- 65		
Single Pulse Avalanche Energy ^a	L = 0.1 IIII	E _{AS}	211	mJ	
Power Dissipation	T _C = 25 °C	P _D	250 ^b	W	
rower Dissipation	T _A = 25 °C	' D	2.4		
Operating Junction and Storage Temperature Range		T _J , T _{stg}	- 55 to 175	°C	

THERMAL RESISTANCE RATINGS					
Parameter	Symbol	Limit	Unit		
Junction-to-Ambient Free Air	R _{thJA}	62	°C/W		
Junction-to-Case	R _{thJC}	0.6			

Notes:

- a. Duty cycle \leq 1 %.
- b. See SOA curve for voltage derating.
- c. Limited by package.

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Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit	
Static							
Drain-Source Breakdown Voltage	V _{DS}	$V_{GS} = 0 \text{ V}, I_D = -250 \mu\text{A}$	- 60			.,	
Gate-Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}, I_{D} = -250 \mu A$	- 1		- 3	V	
Gate-Body Leakage	I _{GSS}	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$			± 100	nA	
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} = - 60 V, V _{GS} = 0 V			- 1	μΑ	
		V _{DS} = - 60 V, V _{GS} = 0 V, T _J = 125 °C			- 50		
		V _{DS} = - 60 V, V _{GS} = 0 V, T _J = 175 °C			- 250		
On-State Drain Current ^a	I _{D(on)}	V _{DS} = - 5 V, V _{GS} = - 10 V	- 120			Α	
Drain-Source On-State Resistance ^a	(-,	V _{GS} = - 10 V, I _D = - 30 A		0.0074	0.0093	Ω	
	n	V_{GS} = - 10 V, I_D = - 30 A, T_J = 125 °C			0.0150		
	R _{DS(on)}	$V_{GS} = -10 \text{ V}, I_D = -30 \text{ A}, T_J = 175 ^{\circ}\text{C}$			0.0190		
		V _{GS} = - 4.5 V, I _D = - 20 A		0.0094	0.0118		
Forward Transconductance ^a	9 _{fs}	V _{DS} = - 15 V, I _D = - 30 A	20			S	
Dynamic ^b	•	·		•			
Input Capacitance	C _{iss}	V _{GS} = 0 V, V _{DS} = - 25 V, f = 1 MHz		9200		pF	
Output Capacitance	C _{oss}			975			
Reverse Transfer Capacitance	C _{rss}			760			
Total Gate Charge ^c	Q_g			160	240	nC	
Gate-Source Charge ^c	Q _{gs}	V _{DS} = - 30 V, V _{GS} = - 10 V, I _D = - 90 A		40			
Gate-Drain Charge ^c	Q _{gd}	1		36			
Gate Resistance	R_{g}	f = 1.0 MHz		3		Ω	
Turn-On Delay Time ^c	t _{d(on)}			20	30	ns ns	
Rise Time ^c	t _r	V_{DD} = - 30 V, R_L = 0.33 Ω I_D \cong - 90 A, V_{GEN} = - 10 V, R_g = 2.5 Ω		190	285		
Turn-Off Delay Time ^c	t _{d(off)}			140	210		
Fall Time ^c	t _f			300	450		
Source-Drain Diode Ratings and Cha	aracteristics	(T _C = 25 °C) ^b					
Continuous Current	I _S				- 90	^	
Pulsed Current	I _{SM}				- 200	Α	
Forward Voltage ^a	V _{SD}	I _F = - 50 A, V _{GS} = 0 V		- 1.0	- 1.5	V	
Reverse Recovery Time	t _{rr}			60	90	ns	
Peak Reverse Recovery Current	I _{RM(REC)}	I _F = - 50 A, dl/dt = 100 A/μs		- 3	- 4.5	Α	
Reverse Recovery Charge	Q _{rr}	1		0.09	0.2	μС	

Notes:

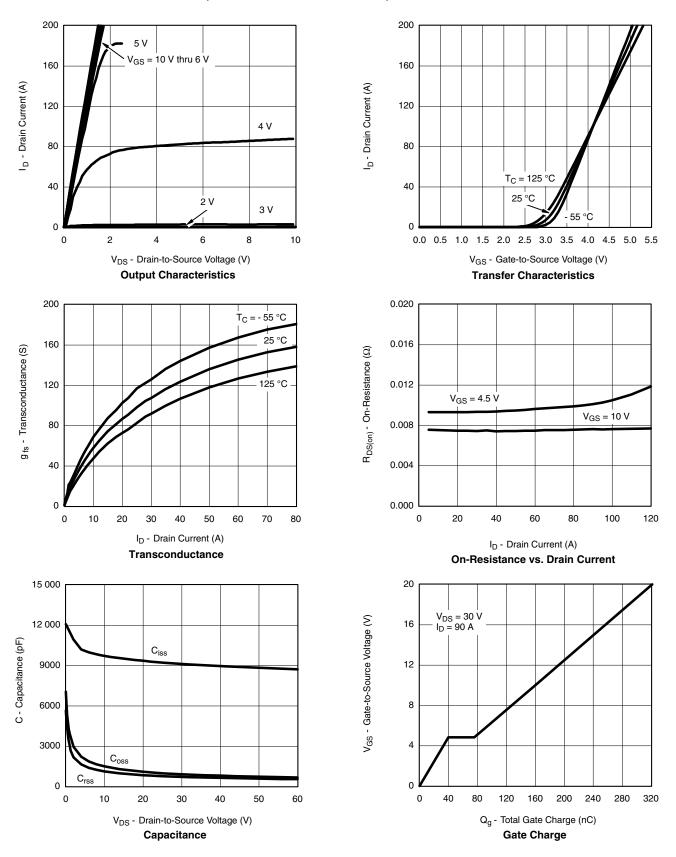
- a. Pulse test; pulse width $\leq 300~\mu s,$ duty cycle $\leq 2~\%.$
- b. Guaranteed by design, not subject to production testing.
- c. Independent of operating temperature.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.





TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

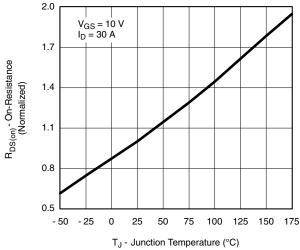


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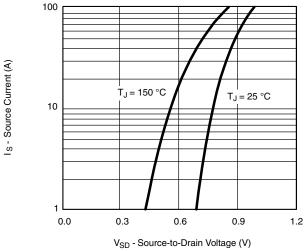
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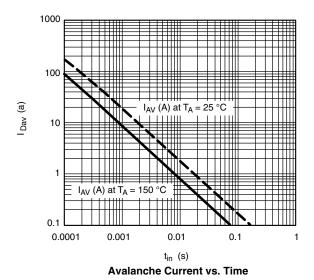
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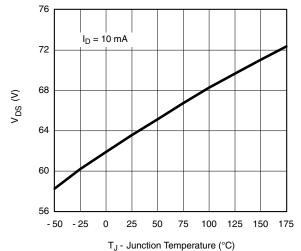


On-Resistance vs. Junction Temperature



Source-Drain Diode Forward Voltage



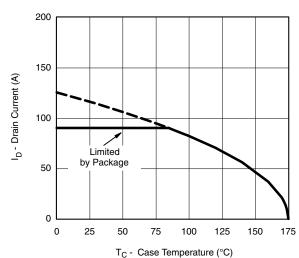


Drain Source Breakdown vs.
Junction Temperature

10 μs

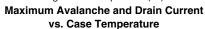


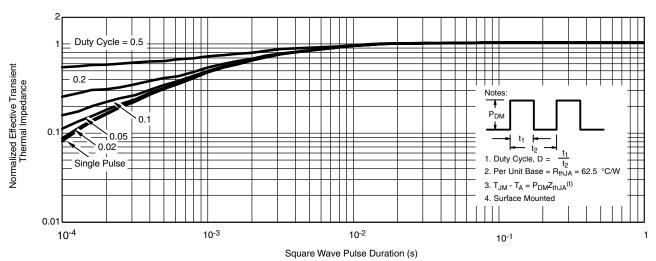
THERMAL RATINGS



 $\begin{array}{c} (\underbrace{Y}) \\ \underbrace{V_{DS}} \\ \underbrace{$

Safe Operating Area





Normalized Thermal Transient Impedance, Junction-to-Case

1000

Limited by R_{DS(on)}

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